

PRODUCT CHANGE NOTICE

1. TITLE Correction to lead length (parameter D3) for WF01G (UT6325 FPGA) package type X, the 208 CQFP.		2. DOCUMENT NUMBER SPO-2016-PCN-0003	
		3. DATE (Year, Month, Date) 2016, November, 03	
4. MANUFACTURER NAME AND ADDRESS CAES 4350 CENTENNIAL BOULEVARD COLORADO SPRINGS, COLORADO 80907-3486		5. MANUFACTURER POINT OF CONTACT NAME Mong Sim	
		6. MANUFACTURER POINT OF CONTACT TELEPHONE 719-594-8446	
		7. MANUFACTURER POINT OF CONTACT EMAIL Mong.Sim@cobhamaes.com	
8. CAGE CODE 65342	9. BLANK	10. PRODUCT IDENTIFICATION CODE WF01G	11. BASE PART UT6325
12. BLANK		13. SMD NUMBER 5962-04229	14. DEVICE TYPE DESIGNATOR 01, 02, 03
		15. RHA LEVELS R, F	16. QML LEVEL Q, V
		17. NON QML LEVEL Prototype, HiRel	18. GIDEP GB4-C-17-0001

19. PRODUCT CHANGE

The 5962-04229 SMD identifies a 208CQFP case outline (X) with a "D3" parameter for the package trimmed lead length, minus the Non-Conductive Strip (NCS or tiebar). The original SMDs (Table 1, revision A and B) identified a nominal D3 value of 0.825 in (20.96 mm). The revised CAES package drawing (Table 2) corrects the nominal D3 trimmed lead length value to 0.620 in (15.755 mm). The revised Table 2 highlights all of the changes and additions to this table.

Figure 1 shows the original 208CQFP drawing from the 5962-04229 SMD, identifying D3. The CAES outline drawing (Figure 2) for the 208CQFP package does not directly identify the D3 lead length. This value must be calculated from the overall package width (parameter D, 75mm), the ceramic body width (parameter D1/E1, 27.991mm) and the NCS width (parameter F, 7.750mm).

Table 1: SMD 208CQFP Original Dimensions and Conversion Table

Case outline X - Continued

Symbol	Dimension (unit: inch)		
	Min.	Nom.	Max.
A			.105
A1			.130
A2			.035
A3			0.115
A4	.030	.035	.040
A5			.035
A6		.050	
b	.006	.008	.010
c	.004	.006	.008
D1/E1	1.094	1.102	1.107
D2/E2		1.004	
D3		.825	
e		.019685	
F	.275	.305	.335
F1		.540	
L			3.000
L1	2.938	2.953	2.968
L2	2.192	2.217	2.242

Inches	mm	Inches	mm
.004	0.10	.335	8.51
.006	0.15	.540	13.72
.008	0.20	.825	20.96
.010	.254	1.004	25.50
.019685	49999	1.094	27.78
.030	.765	1.102	27.99
.035	.889	1.107	28.12
.040	1.02	2.192	55.68
.050	1.27	2.217	56.31
.075	1.91	2.242	56.95
.105	2.67	2.938	74.63
.130	3.30	2.953	75.01
.275	6.99	2.968	75.39
.305	7.75	3.00	76.20

Table 2: New Dimensions Table for 208 CQFP

SMD 208 CQFP package dimensions						
Symbol	inches			mm		
	Min	Nom	Max	Min	Nom	Max
A			0.105			2.667
A1			0.130			3.302
A2			0.035			0.889
A3			0.115			2.921
A4	0.03	0.035	0.040	0.762	0.889	1.106
A5			0.035			0.889
A6		0.05			1.270	
b	0.006	0.008	0.010	0.152	0.203	0.254
c	0.004	0.006	0.008	0.102	0.152	0.203
D1/E1	1.094	1.102	1.107	27.788	27.991	28.118
D2/E2		1.004			25.502	
D3		0.620 typ			15.755 typ	
e		0.019685			0.49999	
F	0.275	0.305	0.335	6.985	7.747	8.509
F1		0.54			13.716	
L			3.000			76.200
L1	2.938	2.953	2.968	74.625	75.006	75.387
L2	2.192	2.217	2.242	55.677	56.312	56.947

20. DISPOSITIONARY RECOMMENDATION:	CHECK & <input type="checkbox"/> USE AS IS	CONTACT <input type="checkbox"/> MANUFACTURER	REMOVE & <input type="checkbox"/> REPLACE	CORRECT & <input type="checkbox"/> USE AS SPECIFIED
21. ADEPT REPRESENTATIVE Lin-Chi Huang	22. SIGNATURE 			23. DATE November 8, 2016

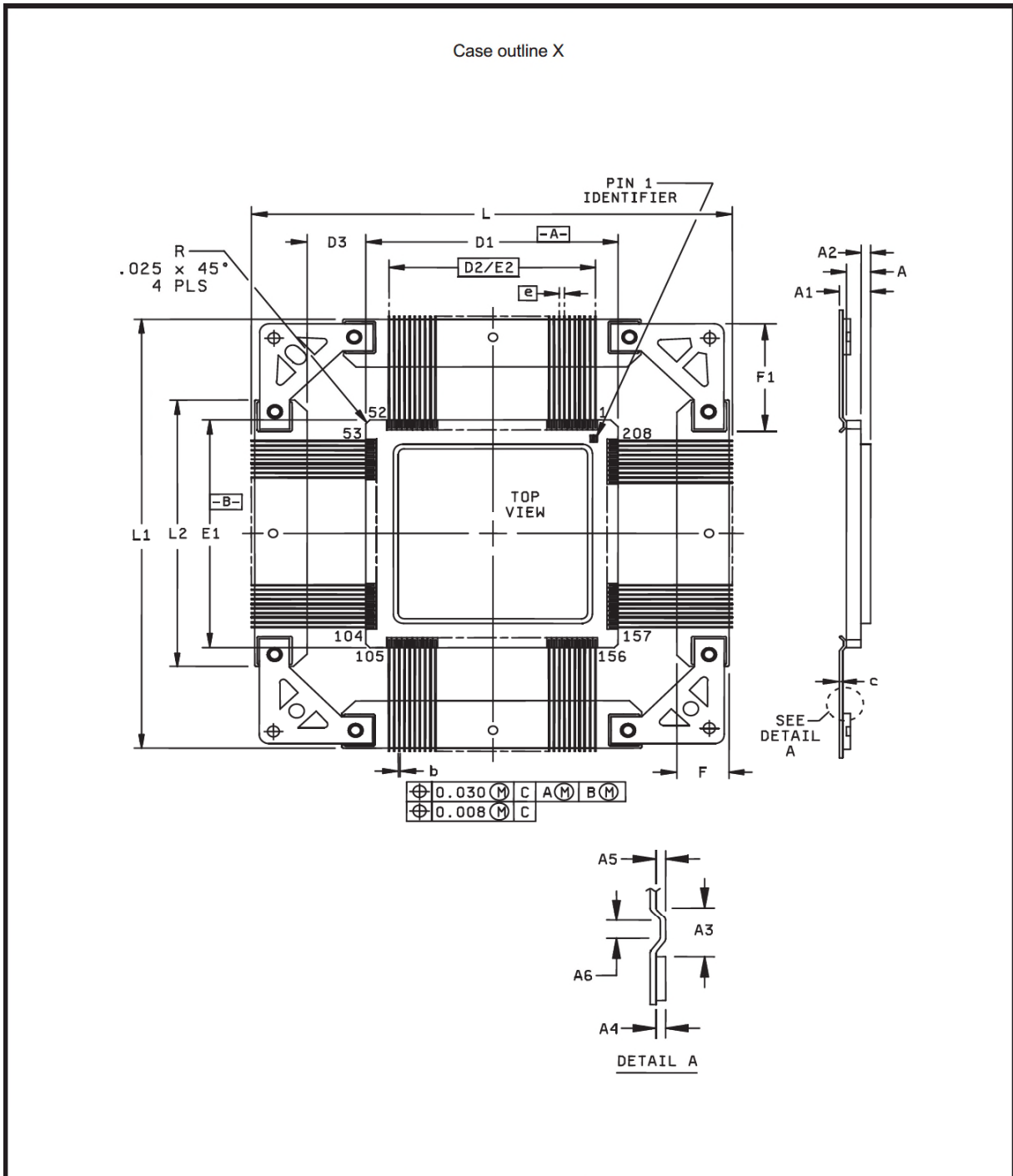


FIGURE 1. Case outlines.

<p>STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990</p>	<p>SIZE A</p>		<p>5962-04229</p>
		<p>REVISION LEVEL B</p>	<p>SHEET 13</p>

Figure 1: SMD 5962-04229 208CQFP Outline Drawing

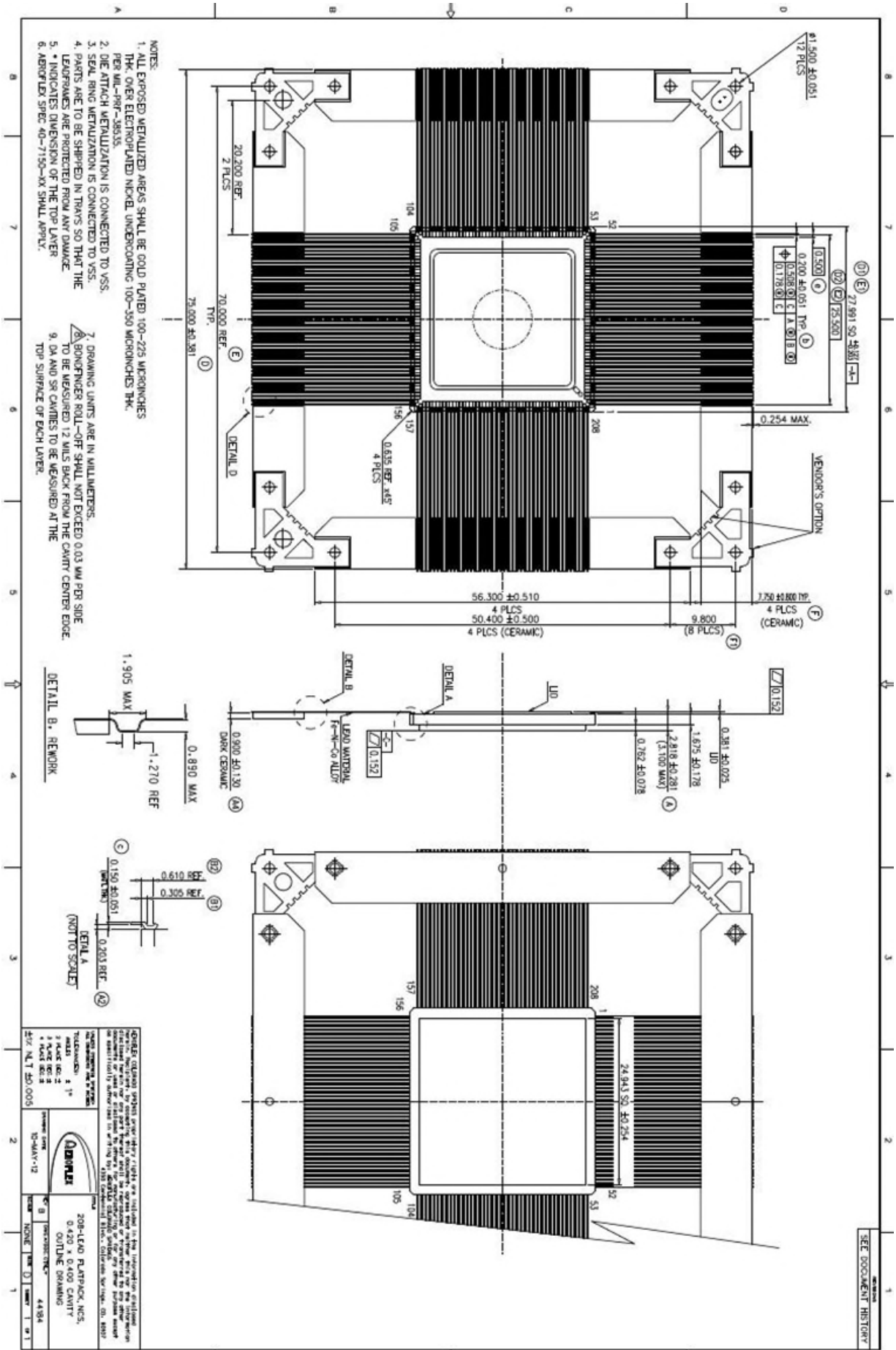


Figure 2: CAES outline drawing for 208CQFP Package